



Dkt. 2271/63282

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of:

Yuji NATORI, et al.

Serial No.:

09/679,747

Group Art Unit: 2854

Date Filed:

October 5, 2000

Examiner: R. Yan

For:

HEAT-SENSITIVE STENCIL, PROCESS OF
FABRICATING SAME AND PRINTER USING SAME

1185 Avenue of the Americas
New York, N.Y. 10036

Assistant Commissioner for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to examination on the merits, please amend the above-identified application

follows:

In the Claims:

Please add claim 18 as follows:

18. (New) A method of preparing a heat-sensitive stencil comprising a porous layer, and a resin film laminated on said porous resin layer, and a thin resin layer interposed between said porous resin layer and said resin film, said thin resin layer and said porous resin layer forming a continuous unitary body, said method comprising the steps of:

I hereby certify that this paper is being deposited this date with the U.S. Postal Service as first class mail addressed to Assistant Commissioner for Patents, Washington, D.C. 20231.

Richard F. Jaworski
Reg. No. 33,515

Feb. 26, 2003
Date

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